- **2-V to 6-V V_{CC} Operation**
- **Inputs Accept Voltages to 6 V**
- **Max t_{pd} of 7.5 ns at 5 V**

SN54AC08 . . . J OR W PACKAGE
SN74AC08 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)

```
        _____
1A [  1    14  ] V_CC
1B [  2    13  ] 4B
1Y [  3    12  ] 4A
2A [  4    11  ] 4Y
2B [  5    10  ] 3B
2Y [  6     9  ] 3A
GND[  7     8  ] 3Y
        _____
```
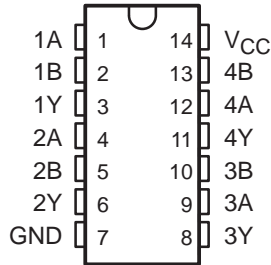
SN54AC08 . . . FK PACKAGE
(TOP VIEW)

```
        1B 1A NC V_CC 4B
         3  2  1  20 19
1Y [  4             18 ] 4A
NC [  5             17 ] NC
2A [  6             16 ] 4Y
NC [  7             15 ] NC
2B [  8             14 ] 3B
         9 10 11 12 13
        2Y GND NC 3Y 3A
```

NC – No internal connection

description/ordering information

The 'AC08 devices are quadruple 2-input positive-AND gates. These devices perform the Boolean function $Y = A \bullet B$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	PDIP – N	Tube	SN74AC08N	SN74AC08N
	SOIC – D	Tube	SN74AC08D	AC08
		Tape and reel	SN74AC08DR	
	SOP – NS	Tape and reel	SN74AC08NSR	AC08
	SSOP – DB	Tape and reel	SN74AC08DBR	AC08
	TSSOP – PW	Tube	SN74AC08PW	AC08
		Tape and reel	SN74AC08PWR	
−55°C to 125°C	CDIP – J	Tube	SNJ54AC08J	SNJ54AC08J
	CFP – W	Tube	SNJ54AC08W	SNJ54AC08W
	LCCC – FK	Tube	SNJ54AC08FK	SNJ54AC08FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	**B**	**Y**
H	H	H
L	X	L
X	L	L

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265
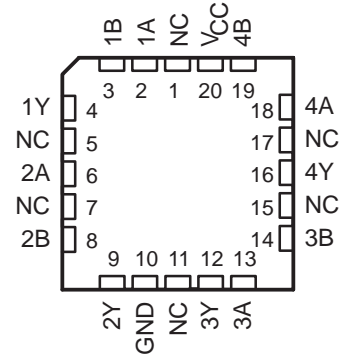
SN54AC08, SN74AC08
QUADRUPLE 2-INPUT POSITIVE-AND GATES

SCAS536D – SEPTEMBER 1995 – REVISED OCTOBER 2003

logic diagram, each gate (positive logic)

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} .... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) .... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) .... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) .... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) .... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) .... ±50 mA
Continuous current through V_{CC} or GND .... ±200 mA
Package thermal impedance, θ_{JA} (see Note 2): D package .... 86°C/W
DB package .... 96°C/W
N package .... 80°C/W
NS package .... 76°C/W
PW package .... 113°C/W
Storage temperature range, T_{stg} .... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54AC08		SN74AC08		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			8		8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_CC	T_A = 25°C			SN54AC08		SN74AC08		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		$I_{OH} = -50\ \mu A$	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		$I_{OH} = -12\ mA$	3 V	2.56			2.4		2.46		
		$I_{OH} = -24\ mA$	4.5 V	3.86			3.7		3.76		
			5.5 V	4.86			4.7		4.76		
		$I_{OH} = -50\ mA$†	5.5 V				3.85				
		$I_{OH} = -75\ mA$†	5.5 V						3.85		
V_{OL}		$I_{OL} = 50\ \mu A$	3 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			5.5 V		0.001	0.1		0.1		0.1	
		$I_{OL} = 12\ mA$	3 V			0.36		0.5		0.44	
		$I_{OL} = 24\ mA$	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		$I_{OL} = 50\ mA$†	5.5 V					1.65			
		$I_{OL} = 75\ mA$†	5.5 V							1.65	
I_I	A or B ports	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μA
I_{CC}		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		40		20	μA
C_i		$V_I = V_{CC}$ or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 3.3\ V \pm 0.3\ V$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC08		SN74AC08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.5	7.5	9.5	1	12.5	1	10	ns
t_{PHL}			1.5	7	8.5	1	11.5	1	9	

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5\ V \pm 0.5\ V$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC08		SN74AC08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.5	5.5	7.5	1	9	1	8.5	ns
t_{PHL}			1.5	5.5	7	1	8.5	1	7.5	

operating characteristics, $V_{CC} = 5\ V$, $T_A = 25°C$

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50\ pF$,	f = 1 MHz	20	pF

TEXAS INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PLH}/t_{PHL}	Open

LOAD CIRCUIT

VOLTAGE WAVEFORMS
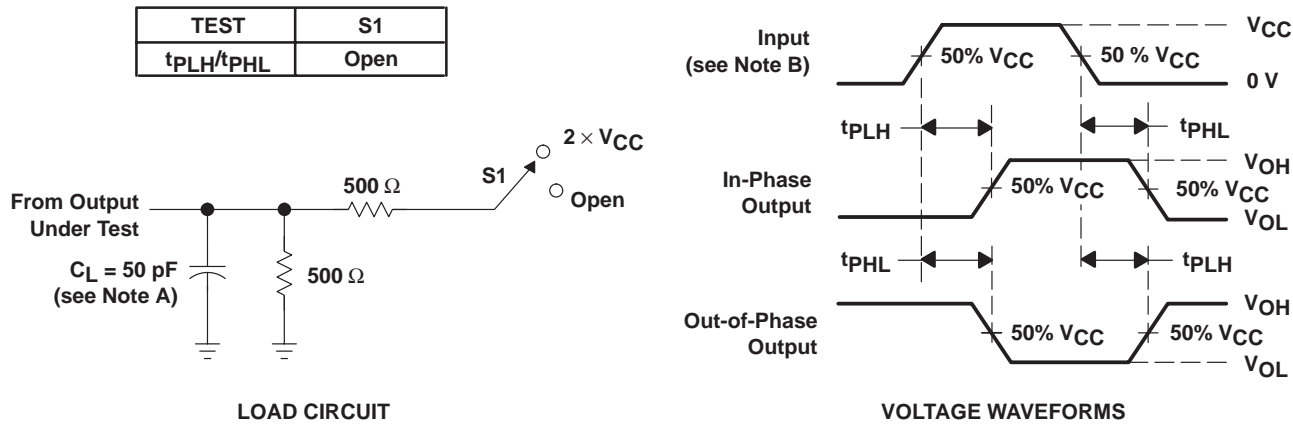
NOTES: A. C_L includes probe and jig capacitance.
    B. All input pulses are supplied by generators having the following characteristics: PRR $\leq$ 1 MHz, Z_O = 50 Ω, $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
    C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87615012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-87615012A SNJ54AC 08FK	Samples
5962-8761501CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8761501CA SNJ54AC08J	Samples
5962-8761501DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8761501DA SNJ54AC08W	Samples
SN74AC08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	Samples
SN74AC08DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	Samples
SN74AC08DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	Samples
SN74AC08DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	Samples
SN74AC08N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC08N	Samples
SN74AC08NE4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC08N	Samples
SN74AC08NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	Samples
SN74AC08PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	Samples
SN74AC08PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	Samples
SN74AC08PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	Samples
SNJ54AC08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-87615012A SNJ54AC 08FK	Samples
SNJ54AC08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8761501CA SNJ54AC08J	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54AC08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8761501DA SNJ54AC08W	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54AC08, SN74AC08 :

● Catalog: SN74AC08

![Texas Instruments logo]

24-Aug-2018

- Automotive: SN74AC08-Q1, SN74AC08-Q1

- Enhanced Product: SN74AC08-EP, SN74AC08-EP

- Military: SN54AC08

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

- Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC08DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74AC08DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AC08PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

![TEXAS INSTRUMENTS] **PACKAGE MATERIALS INFORMATION**

TAPE AND REEL BOX DIMENSIONS
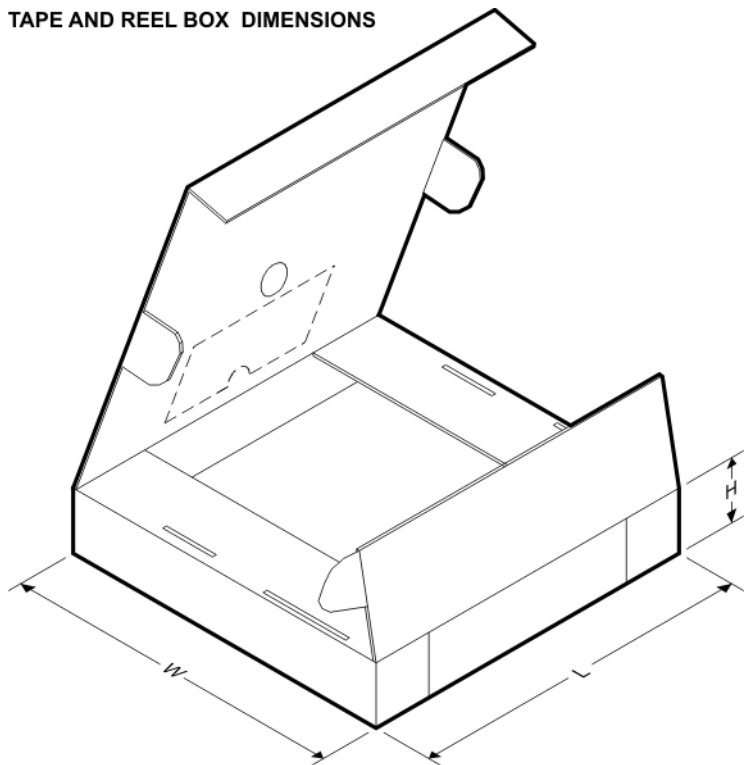
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC08DBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74AC08DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74AC08PWR	TSSOP	PW	14	2000	367.0	367.0	35.0

FK (S−CQCC−N**)   LEADLESS CERAMIC CHIP CARRIER
28 TERMINAL SHOWN
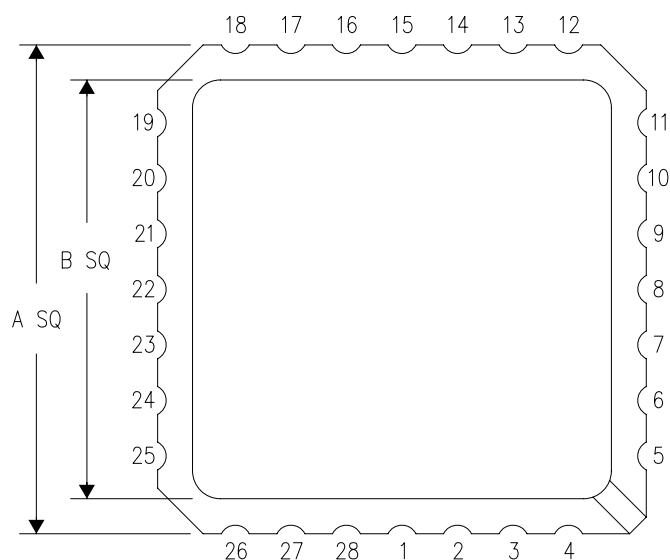
NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)
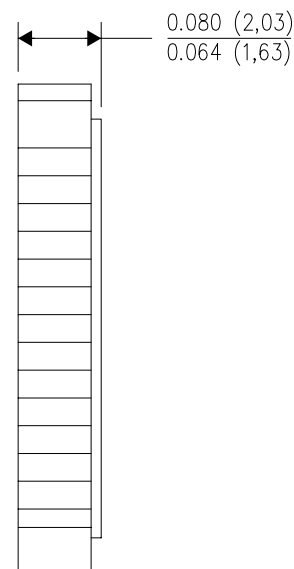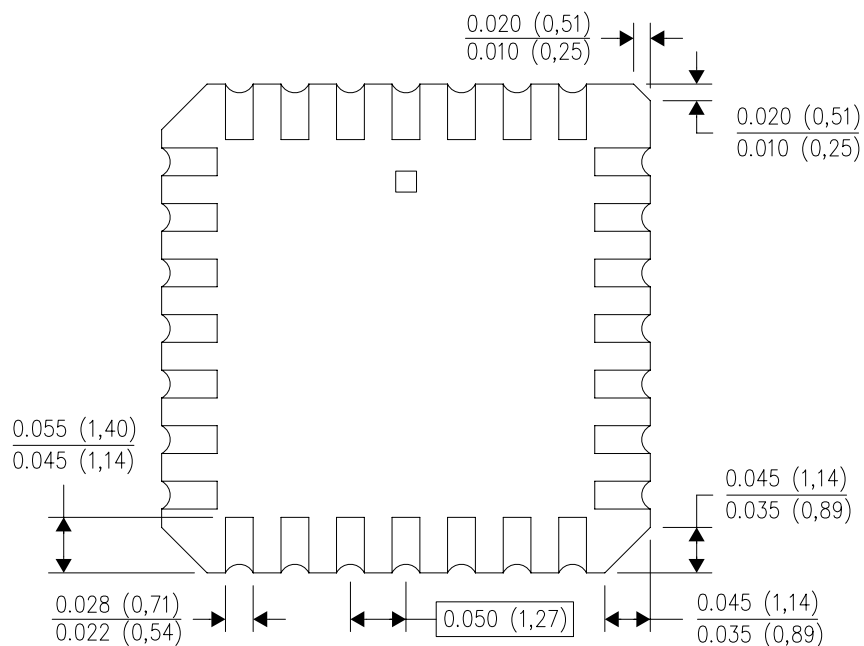
4040140/D 01/11

NOTES: A.   All linear dimensions are in inches (millimeters).
           B.   This drawing is subject to change without notice.
           C.   This package can be hermetically sealed with a metal lid.
           D.   Falls within JEDEC MS−004

MECHANICAL DATA

NS (R-PDSO-G**)   PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN
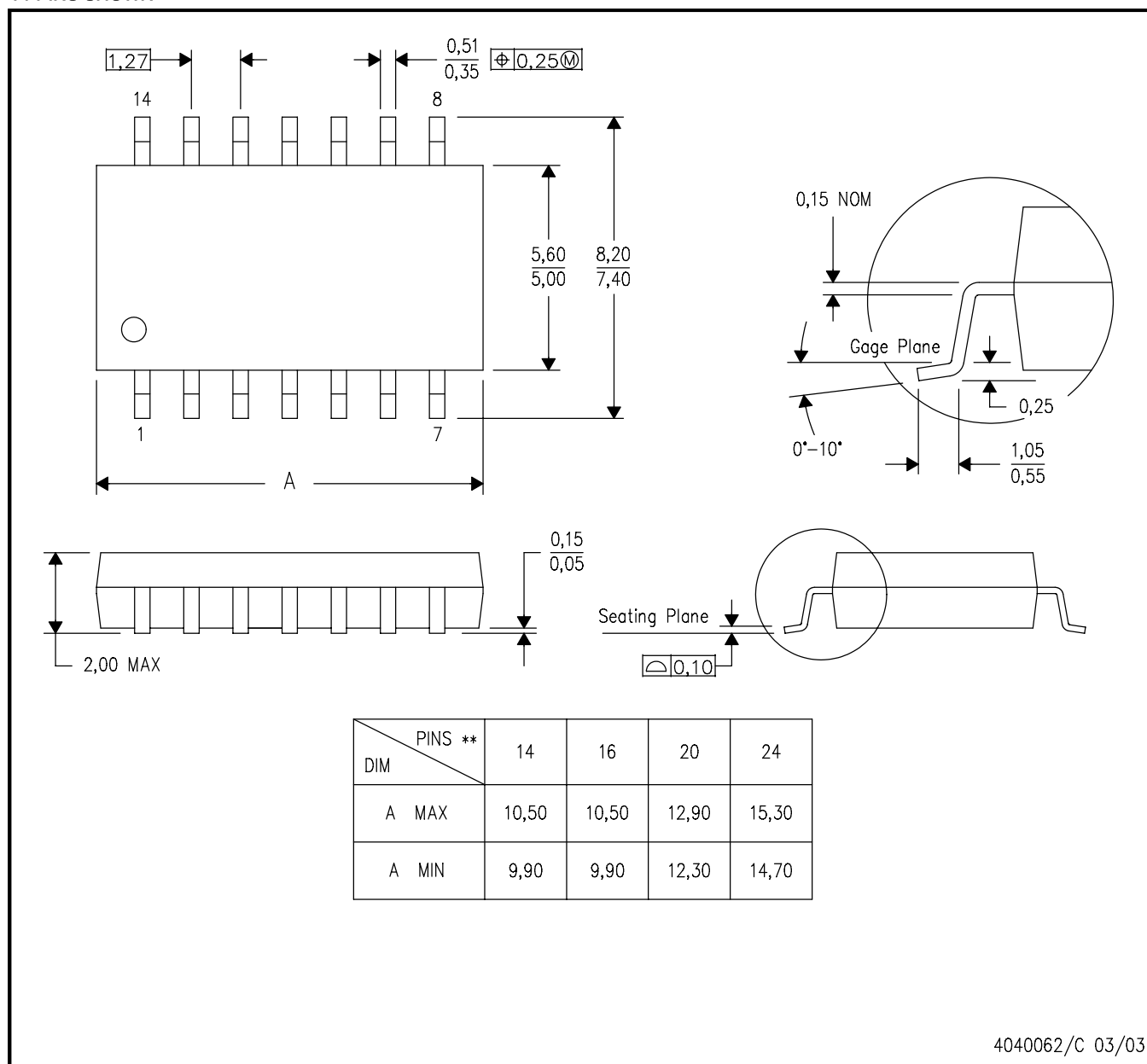
1,27

0,51
0,35   ⊕ 0,25 Ⓜ

14   8

5,60   8,20
5,00   7,40

1   7

A

0,15 NOM

Gage Plane

0,25

0°–10°

1,05
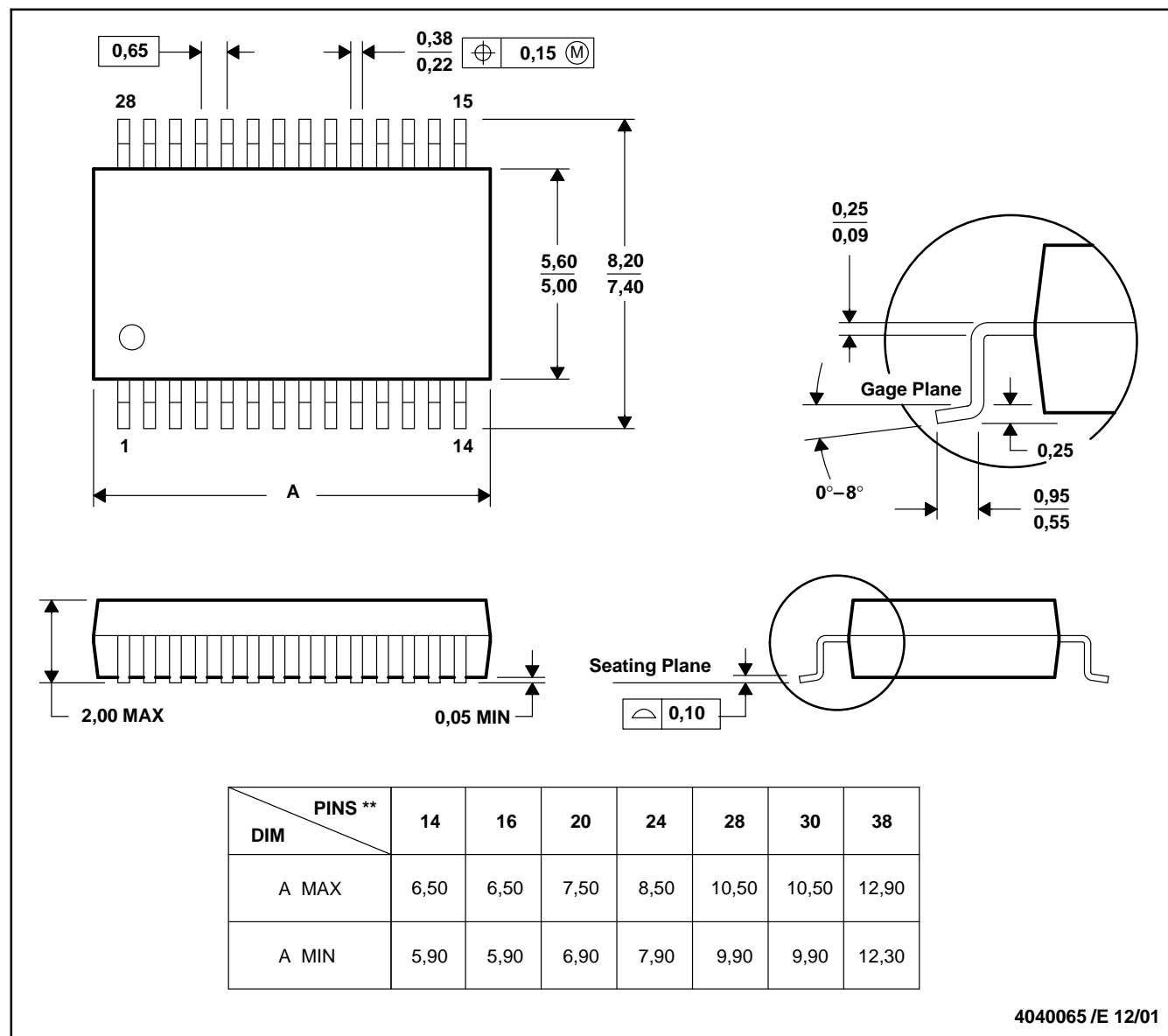0,55

0,15
0,05

2,00 MAX

Seating Plane

◇ 0,10

DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R–GDFP–F14)   CERAMIC DUAL FLATPACK

Base and Seating Plane

0.045 (1,14)
0.026 (0,66)

0.260 (6,60)
0.235 (5,97)

0.080 (2,03)
0.045 (1,14)

0.008 (0,20)
0.004 (0,10)

0.280 (7,11) MAX

1   14

0.019 (0,48)
0.015 (0,38)

0.050 (1,27)

0.390 (9,91)
0.335 (8,51)

0.005 (0,13) MIN
4 Places

7   8

0.360 (9,14)
0.250 (6,35)

0.360 (9,14)
0.250 (6,35)

4040180–2/F   04/14

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. This package can be hermetically sealed with a ceramic lid using glass frit.
        D. Index point is provided on cap for terminal identification only.
        E. Falls within MIL STD 1835 GDFP1–F14

TEXAS
INSTRUMENTS

Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

TEXAS
INSTRUMENTS

PIN 1 ID
(OPTIONAL)

A

1

14

12X .100
[2.54]

7

8

.754-.785
[19.15-19.94]

B

.245-.283
[6.22-7.19]

4X .005 MIN
[0.13]

.015-.060 TYP
[0.38-1.52]

14X .045-.065
[1.15-1.65]

14X .014-.026
[0.36-0.66]

⊕ .010 [0.25] C A B

.2 MAX TYP
[5.08]

.13 MIN TYP
[3.3]

C

SEATING PLANE

.308-.314
[7.83-7.97]
AT GAGE PLANE

.015
[0.38]

GAGE PLANE

0°-15°
TYP

14X .008-.014
[0.2-0.36]
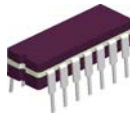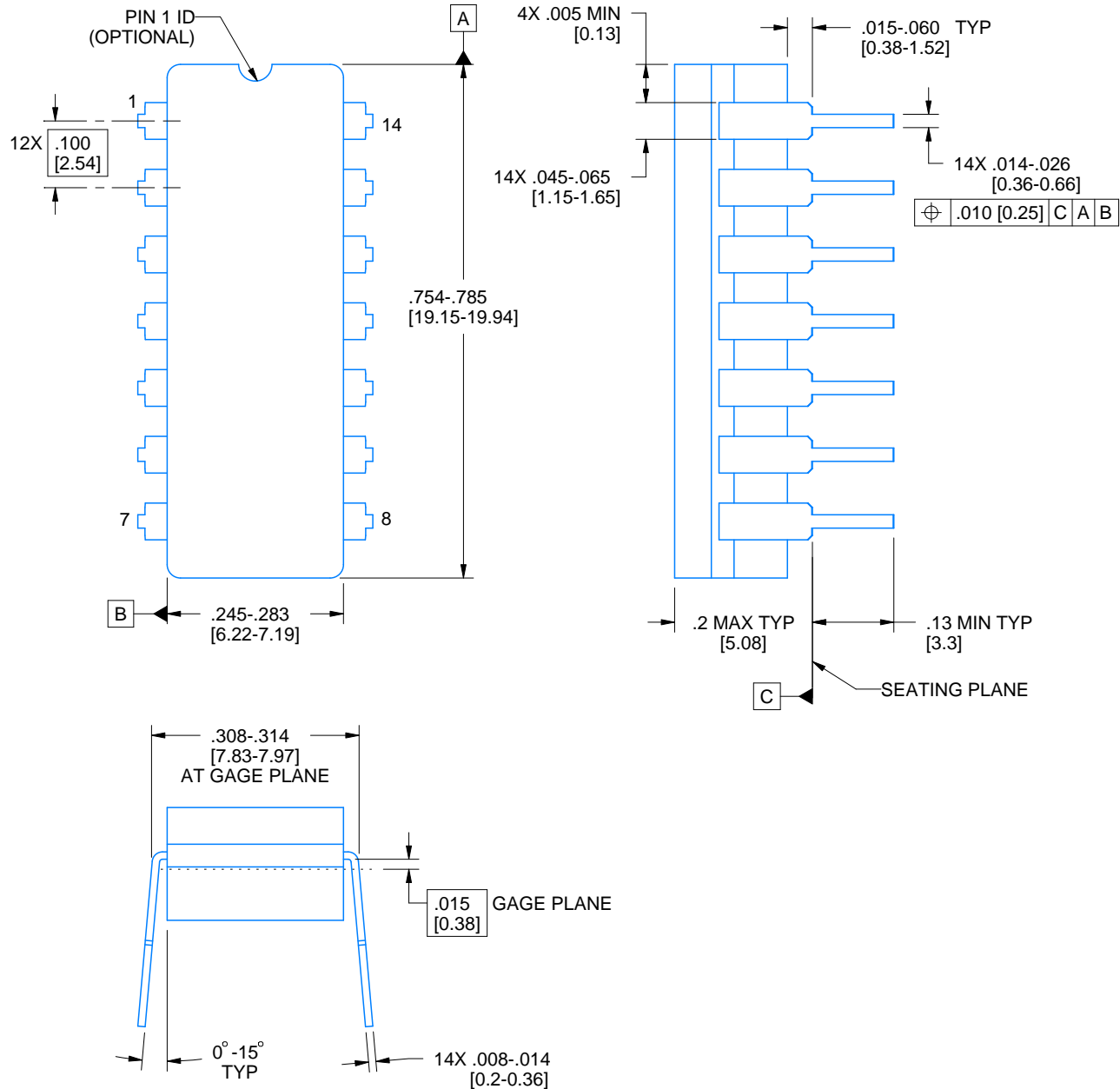
4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

SEE DETAIL A

SEE DETAIL B

(.300) TYP
[7.62]

1

14

12X (.100)
[2.54]

SYMM
$\mathbb{C}$

14X ($\emptyset$ .039)
[1]

7

8

SYMM
$\mathbb{C}$
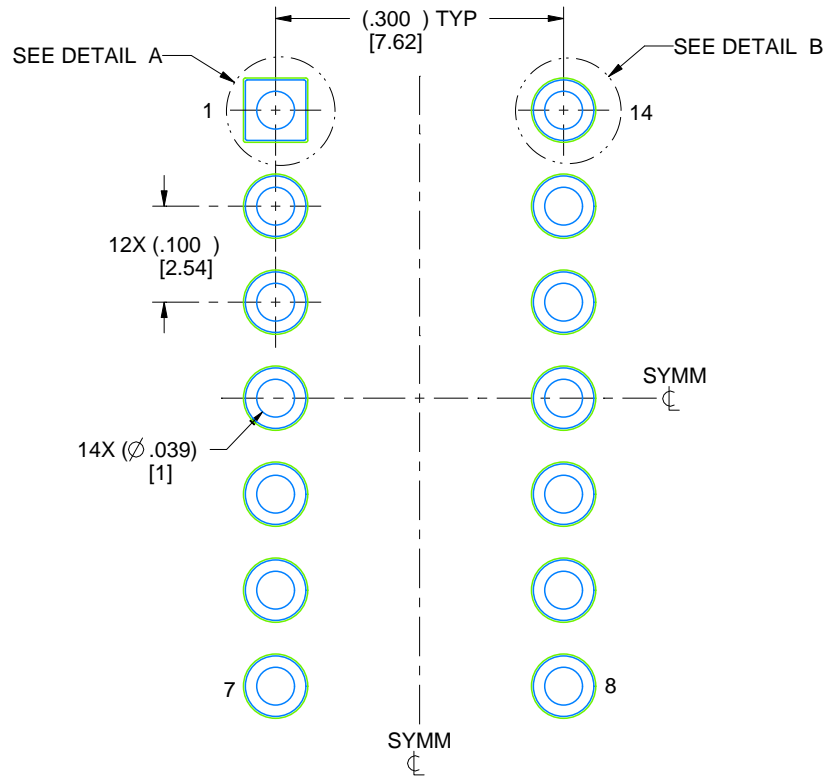
LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X

.002 MAX
[0.05]
ALL AROUND

(.063)
[1.6]

SOLDER MASK
OPENING

METAL

(R.002) TYP
[0.05]

DETAIL A
SCALE: 15X

METAL

($\emptyset$ .063)
[1.6]

SOLDER MASK
OPENING

.002 MAX
[0.05]
ALL AROUND

DETAIL B
13X, SCALE: 15X
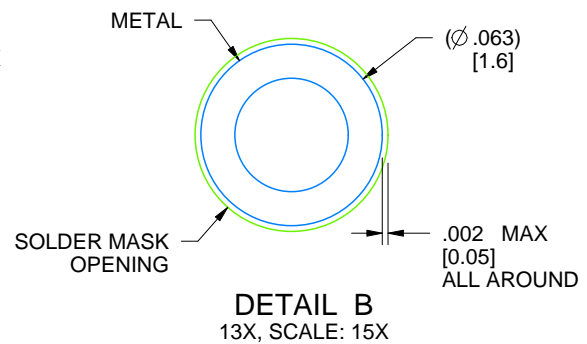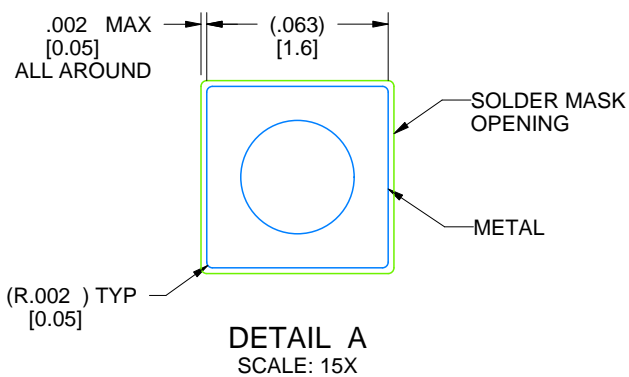
4214771/A 05/2017

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE
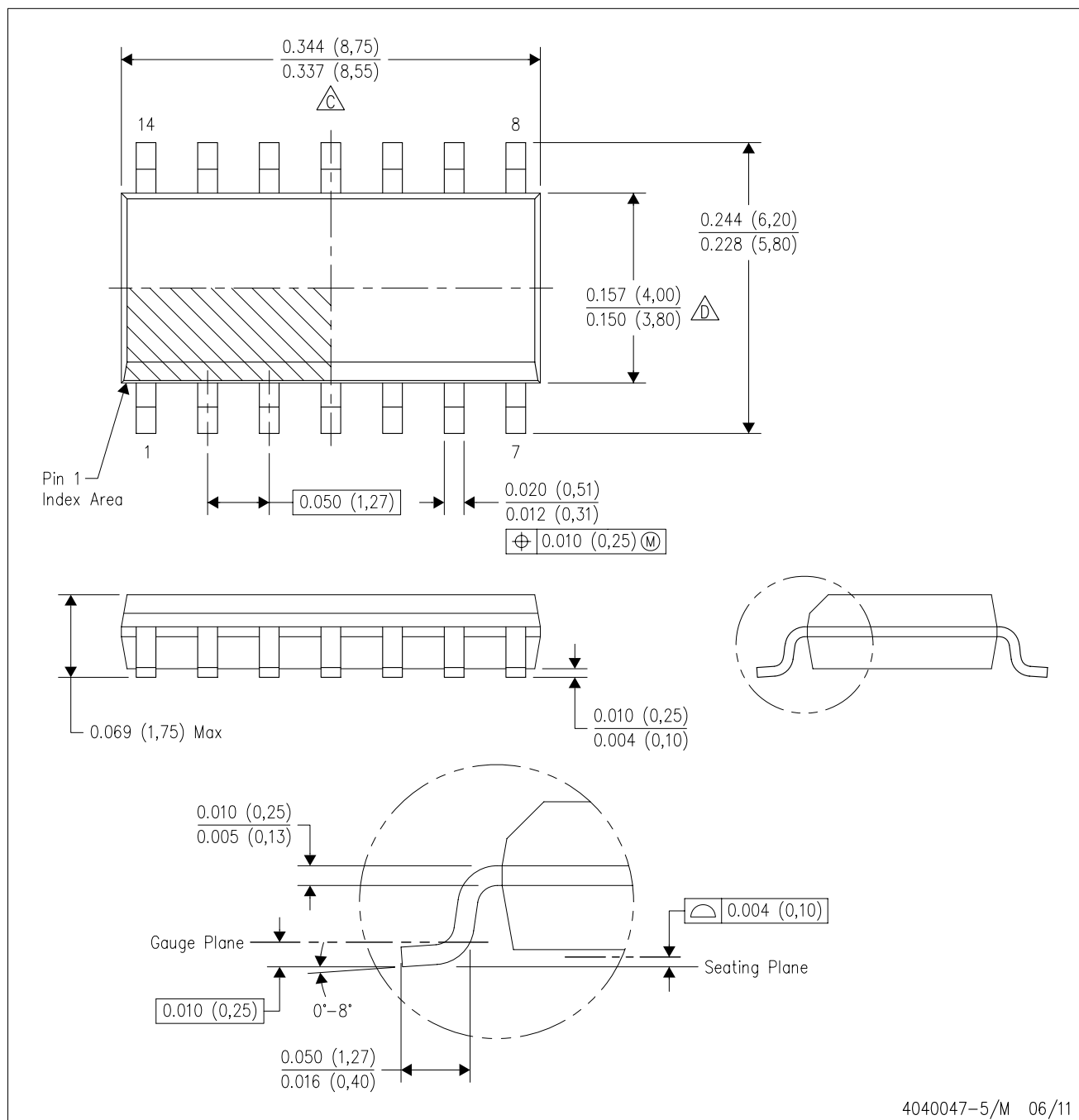
0.344 (8,75)
0.337 (8,55)
C

14   8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80)
D

1   7

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) M

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−5/M   06/11

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed 0.006 (0,15) each side.
         D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
         E. Reference JEDEC MS−012 variation AB.
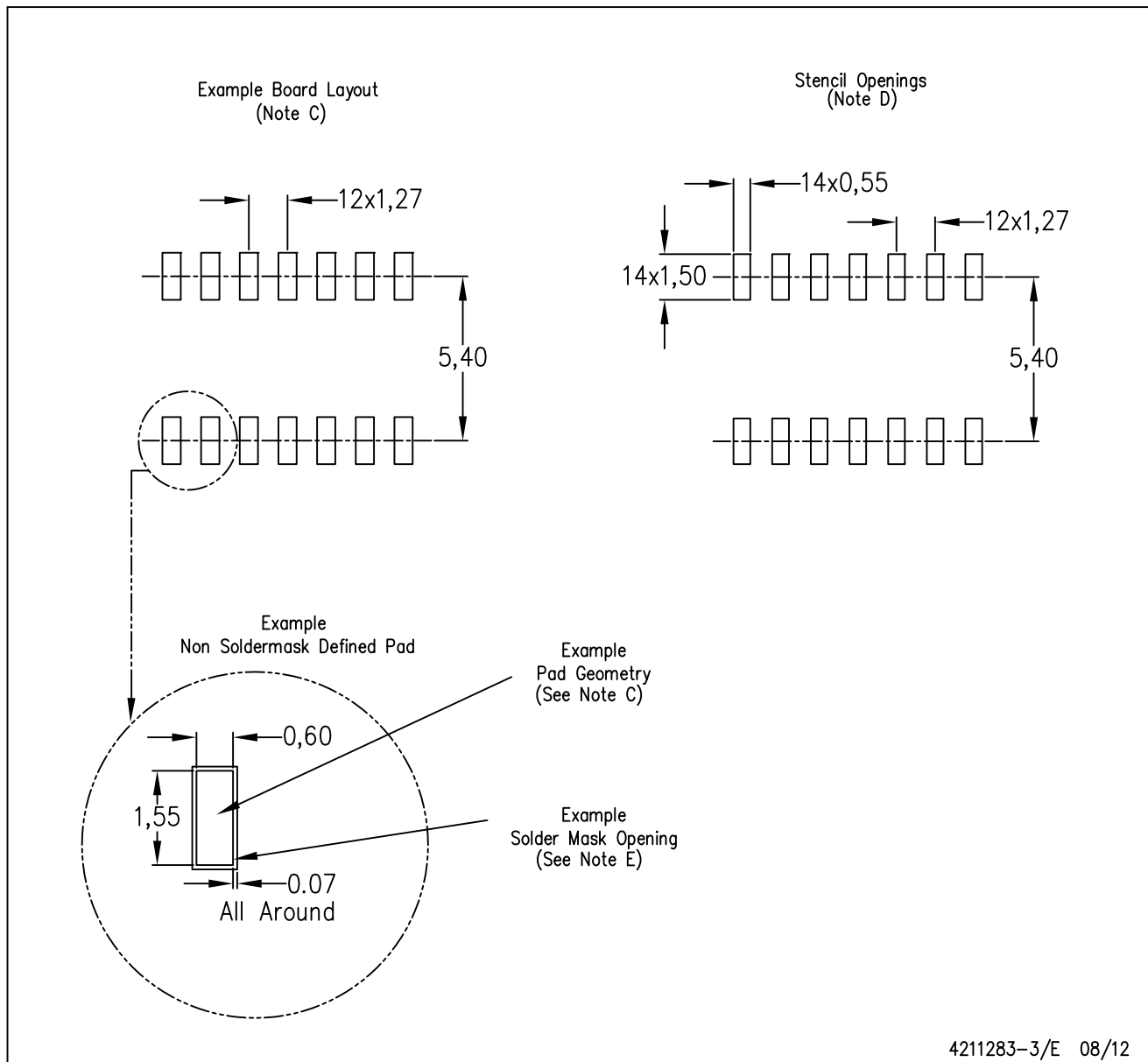
TEXAS INSTRUMENTS
www.ti.com

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

12x1,27

14x0,55

12x1,27

14x1,50

5,40

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

1,55

Example
Solder Mask Opening
(See Note E)

0.07
All Around

4211283−3/E 08/12

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC−7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

TEXAS
INSTRUMENTS
www.ti.com

PW (R−PDSO−G14)   PLASTIC SMALL OUTLINE

0,65

0,30
0,19

⊕ | 0,10 Ⓜ

14   8

Ⓓ 4,50
   4,30

6,60
6,20

1   7

5,10
4,90

Ⓒ

0,15 NOM

Gage Plane

0,25

0°−8°

0,75
0,50

1,20 MAX

0,15
0,05

Seating Plane

△ | 0,10

4040064−3/G 02/11
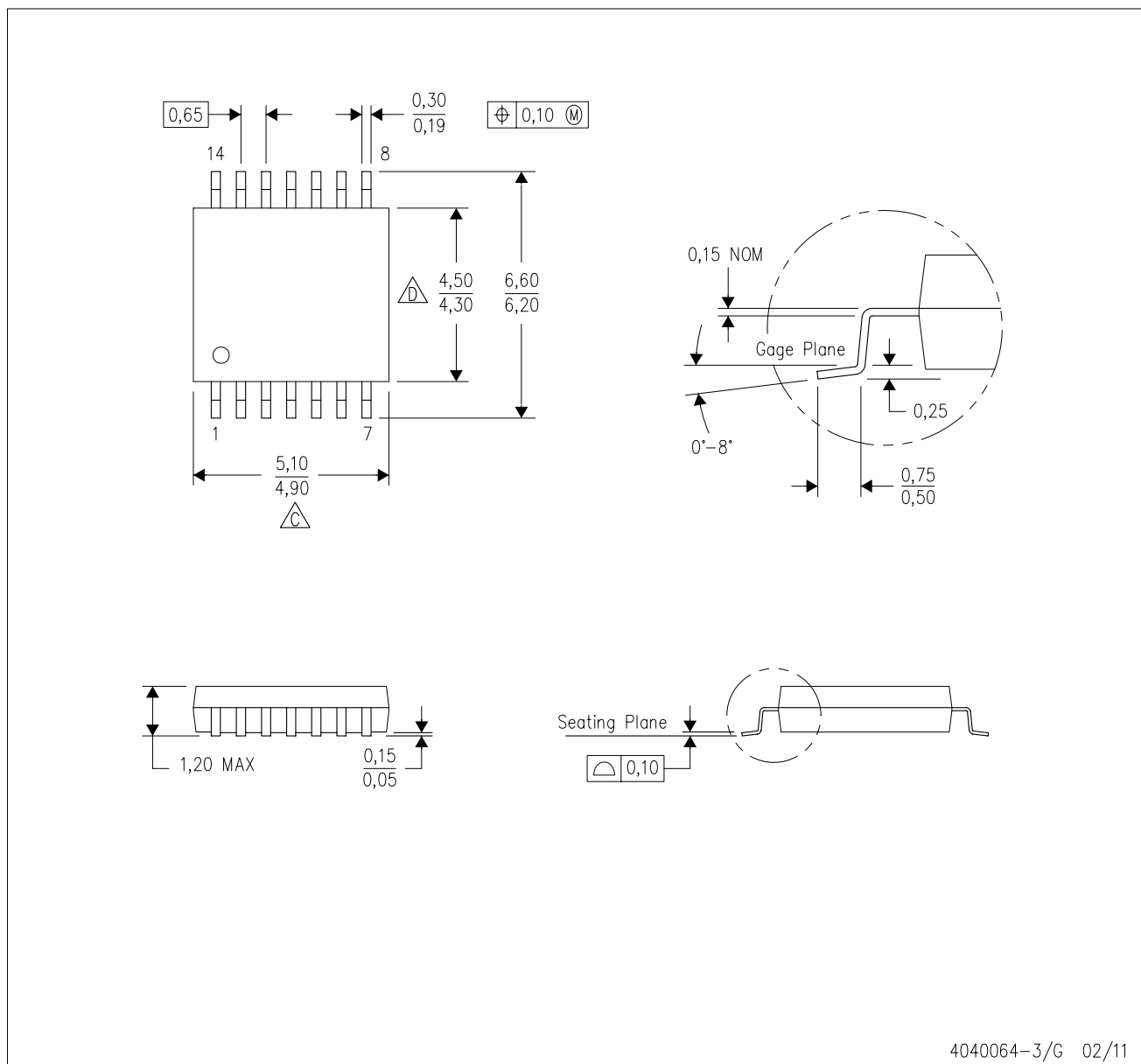
NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
        B. This drawing is subject to change without notice.
        Ⓒ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
            not exceed 0,15 each side.
        Ⓓ Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
        E. Falls within JEDEC MO−153

N (R−PDIP−T**)
16 PINS SHOWN

PLASTIC DUAL−IN−LINE PACKAGE
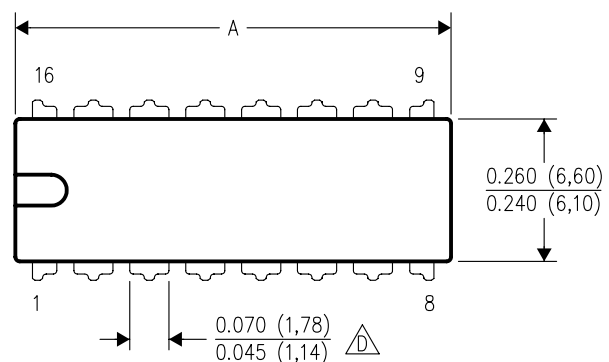
PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
△C △ MS−001 VARIATION	AA	BB	AC	AD

A

16   9

0.260 (6,60)
0.240 (6,10)

1   8

0.070 (1,78)
0.045 (1,14) △D

0.045 (1,14) △D
0.030 (0,76)

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option △D

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E 12/2002

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
     △C △   Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
     △D △   The 20 pin end lead shoulder width is a vendor option, either half or full width.

TEXAS
INSTRUMENTS
www.ti.com

DB (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN

PINS ** DIM	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
        D. Falls within JEDEC MO-150

IMPORTANT NOTICE

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Texas Instruments](#):
   SN74AC08DBRE4 SN74AC08NSRE4 SN74AC08PWE4 SN74AC08DBRG4